

ABSTRACT

A semiconductor element (111) with electrodes (112), and a passive element (113) with electrodes (113a) are embedded in a thermoplastic sheet base (115), which is
5 then subjected to laser beam machining, electron beam machining or ion beam machining to expose electrodes (112 and 113a). Thereafter, a circuit pattern (119) is formed by formation of a thin film or printing of a conductive adhesive. Exposing the electrodes by laser beam machining
10 or the like can be carried out in a short period of time and also by local treatment, thereby reducing damage to the base.